

CSM110: PCI 3.0



Libraries

Name	Process	Form Factor	Silicon proven
RGO_CSM110_33V_NOM_30C_PCI	NOM	staggered	yes
RGO_CSM110_33V_NOM_50C_PCI	NOM	Inline	yes

Summary

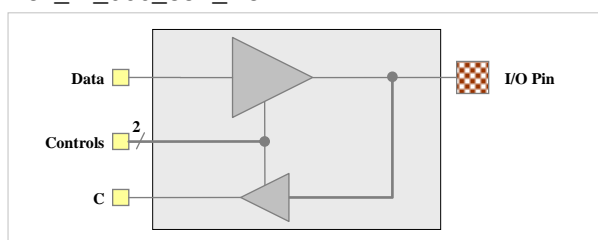
These pads are compatible with PCI Local Bus Specification Revision 3.0 for 3.3V signaling. Cell can be used for both 33MHz and 66MHz operation.

ESD Protection

I/O pads are designed with robust ESD protection for all market segments. Passed:

- 2KV ESD Human Body Model (HBM)
- 200 V ESD Machine Model (MM)
- 500 V ESD Charge Device Model (CDM)

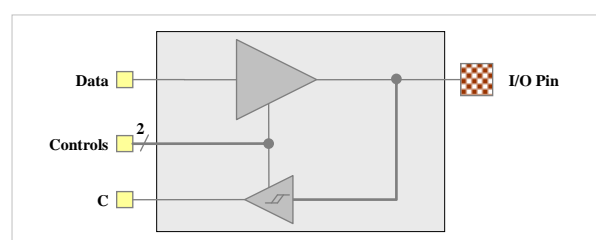
PCx_BI_066_33V_NCW



Description

PCI 3.0 pad without Schmitt trigger.

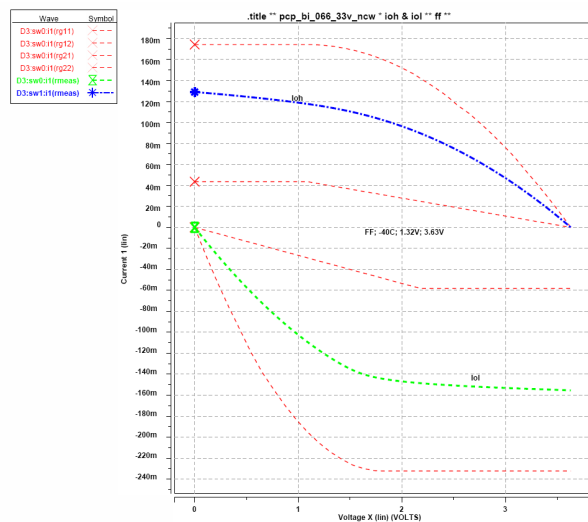
PCx_BI_066_33V_SCW



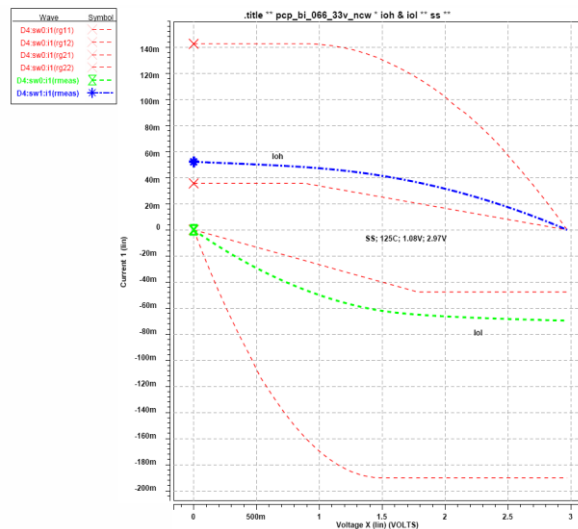
Description

PCI 3.0 pad with Schmitt trigger.

IOH / IOL (FF corner)



IOH / IOL (SS corner)



Recommended operating conditions

Description	Min	Nom	Max	Units
V _{DVDD} I/O supply voltage	2.97	3.3	3.63	V
T _A Ambient operating temperature	0	25	100	°C
V _{VDD} Core supply voltage	1.08	1.2	1.32	V
T _J Junction temperature	-40	25	125	°C
V _{PAD} Voltage at PAD	0	-	V _{DVDD}	V
V _{IH} Input logic high	0.7 * V _{DVDD}		V _{DVDD} + 0.3	V
V _{IL} Input logic low	V _{DVSS} - 0.3		0.3 * V _{DVDD}	V

Characterization Corners

Nominal VDD	Model	VDD	DVDD=3.3V	Temperature
1.2	FF	+10%	+10%	-40°C
	FF	+10%	+10%	125°C
	TT	nominal	nominal	25°C
	SS	-10%	-10%	-40°C
	SS	-10%	-10%	125°C

© 2010 Aragio Solutions. All rights reserved.

Information in this document is subject to change without notice. Aragio Solutions may have patents, patent applications, trademarks, copyrights or other intellectual property rights covering subject matter in this document. Except as expressly provided in any written license agreement from Aragio, the furnishing of this document does not give you any license to the patents, trademarks, copyrights, or other intellectual property.

Published by:

Aragio Solutions
2201 K Avenue
Section B Suite 200
Plano, TX 75074-5918
Phone: (972) 516-0999
Fax: (972) 516-0998
Web: <http://www.aragio.com/>

While every precaution has been taken in the preparation of this book, the publisher assumes no responsibility for errors or omissions, or for damages resulting from the use of the information contained herein. This document may be reproduced and distributed in whole, in any medium, physical or electronic, under the terms of a license or nondisclosure agreement with Aragio.

Printed in the United States of America